

VQ1006 SERIES

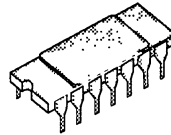


N-Channel Enhancement-Mode MOS Transistor Arrays

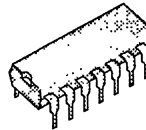
PRODUCT SUMMARY

PART NUMBER	$V_{(BR)DSS}$ (V)	$r_{DS(ON)}$ (Ω)	I_D (A)	PACKAGE
VQ1006J	90	4.5	0.40	Plastic
VQ1006P	90	4.5	0.40	Side Braze

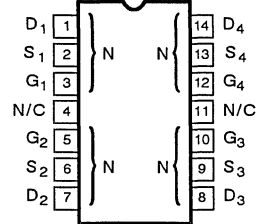
14-PIN DIP
SIDE BRAZE



14-PIN PLASTIC



TOP VIEW
Dual-In-Line Package



Performance Curves: VNDQ09 (See Section 7)

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	VQ1006J	VQ1006P	UNITS
Drain-Source Voltage	V_{DS}	90	90	V
Gate-Source Voltage	V_{GS}	± 30	± 20	
Continuous Drain Current	I_D	$T_A = 25^\circ\text{C}$	0.40	A
		$T_A = 100^\circ\text{C}$	0.23	
Pulsed Drain Current ¹	I_{DM}	± 2	± 2	
Power Dissipation – Single	P_D	$T_A = 25^\circ\text{C}$	1.3	W
		$T_A = 100^\circ\text{C}$	0.52	
Power Dissipation – Quad	P_D	$T_A = 25^\circ\text{C}$	2	W
		$T_A = 100^\circ\text{C}$	0.8	
Operating Junction and Storage Temperature	T_J, T_{stg}	-55 to 150		$^\circ\text{C}$
Lead Temperature (1/16" from case for 10 seconds)	T_L	300		

THERMAL RESISTANCE

THERMAL RESISTANCE	SYMBOL	VQ1006J	VQ1006P	UNITS
Junction-to-Ambient – Single	R_{thJA}	96.2	96.2	$^\circ\text{C}/\text{W}$
Junction-to-Ambient – Quad		62.5	62.5	

¹Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS ¹				LIMITS			
PARAMETER	SYMBOL	TEST CONDITIONS	VQ1006			UNIT	
			TYP ²	MIN	MAX		
STATIC							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}, I_D = 10\ \mu\text{A}$	120	90		V	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 1\text{ mA}$	1.6	0.8	2.5		
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}$ $V_{GS} = \pm 15\text{ V}$ $T_J = 125^\circ\text{C}$	± 1 ± 5		± 100 ± 500	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 90\text{ V}$ $V_{GS} = 0\text{ V}$ $V_{DS} = 72\text{ V}, T_J = 125^\circ\text{C}$	0.03 0.3		1 500	μA	
On-State Drain Current ³	$I_{D(ON)}$	$V_{DS} = 10\text{ V}, V_{GS} = 10\text{ V}$	1.8	1.5		A	
Drain-Source On-Resistance ³	$r_{DS(ON)}$	$V_{GS} = 5\text{ V}, I_D = 0.3\text{ A}$	4.7		5	Ω	
		$V_{GS} = 10\text{ V}$ $I_D = 1\text{ A}$ ⁴ $T_J = 125^\circ\text{C}$	4.1 7.7		4.5 8.6		
Forward Transconductance ³	g_{FS}	$V_{DS} = 10\text{ V}, I_D = 0.5\text{ A}$	350	170		mS	
Common Source Output Conductance ³	g_{OS}	$V_{DS} = 10\text{ V}, I_D = 0.1\text{ A}$	225			μS	
DYNAMIC							
Input Capacitance	C_{iss}	$V_{DS} = 25\text{ V}$ $V_{GS} = 0\text{ V}$ $f = 1\text{ MHz}$	35		60	pF	
Output Capacitance	C_{oss}		15		50		
Reverse Transfer Capacitance	C_{rss}		2		10		
SWITCHING							
Turn-On Time	t_{ON}	$V_{DD} = 25\text{ V}, R_L = 23\ \Omega$ $I_D = 1\text{ A}, V_{GEN} = 10\text{ V}$ $R_G = 25\ \Omega$ (Switching time is essentially independent of operating temperature)	6		10	ns	
Turn-Off Time	t_{OFF}		8		10		

- NOTES: 1. $T_A = 25^\circ\text{C}$ unless otherwise noted.
2. For design aid only, not subject to production testing.
3. Pulse test; $PW = 300\ \mu\text{s}$, duty cycle $\leq 2\%$.
4. This parameter has been revised from previous data sheet.